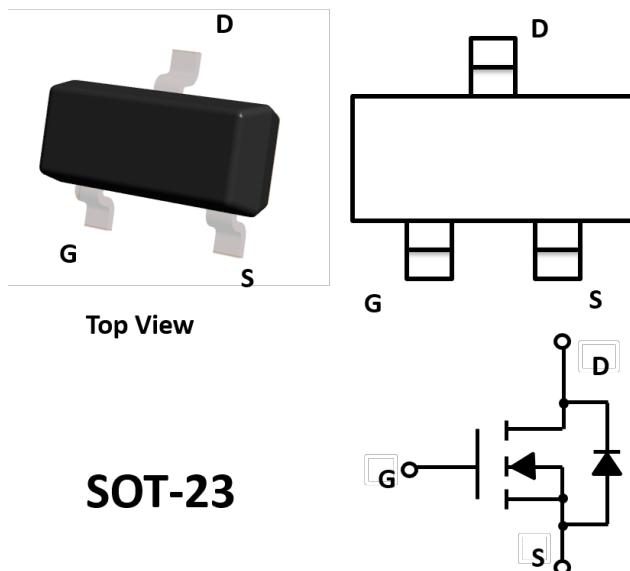


N-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} 50V
- I_D 340mA
- $R_{DS(ON)}$ (at $V_{GS}=10V$) < 2.5ohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) < 3.0ohm

General Description

- Trench Power MV MOSFET technology
- Voltage controlled small signal switch
- Low input Capacitance
- Fast Switching Speed
- Low Input / Output Leakage

Applications

- Battery operated systems
- Solid-state relays
- Direct logic-level interface: TTL/CMOS

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	50	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^\circ C$ @ Steady State	I_D	340	mA
	$T_A=70^\circ C$ @ Steady State		272	
Pulsed Drain Current ^A		I_{DM}	1.5	A
Total Power Dissipation @ $T_A=25^\circ C$		P_D	350	mW
Thermal Resistance Junction-to-Ambient @ Steady State ^B		$R_{\theta JA}$	357	$^\circ C / W$
Junction and Storage Temperature Range		T_J, T_{STG}	-55 ~ +150	$^\circ C$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BSS138	F2	SS.	3000	45000	180000	7" reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	50			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS1}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
	I_{GSS2}	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$			± 50	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.8	1.2	1.6	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=-300\text{mA}$		1.1	2.5	Ω
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=200\text{mA}$		1.2	3.0	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=300\text{mA}, V_{\text{GS}}=0\text{V}$			1.2	V
Maximum Body-Diode Continuous Current	I_{S}				340	mA
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		17.5		pF
Output Capacitance	C_{oss}			11.5		
Reverse Transfer Capacitance	C_{rss}			6.5		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=25\text{V}, I_{\text{D}}=0.3\text{A}$		1.7	2.4	nC
Turn-on Delay Time	$t_{\text{D(on)}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=25\text{V}, I_{\text{D}}=300\text{mA}, R_{\text{GEN}}=6\Omega$		5		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			17		
Reverse recovery Time	t_{rr}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=300\text{mA}, V_{\text{R}}=25\text{V}, dI_{\text{S}}/dt=-100\text{A}/\mu\text{s}$		30		ns

A. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

■ Typical Performance Characteristics

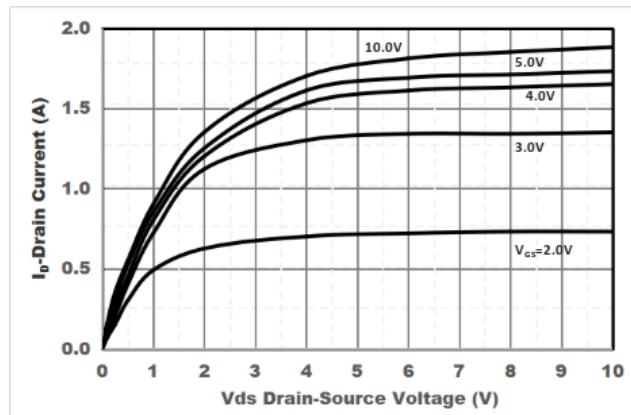


Figure1. Output Characteristics

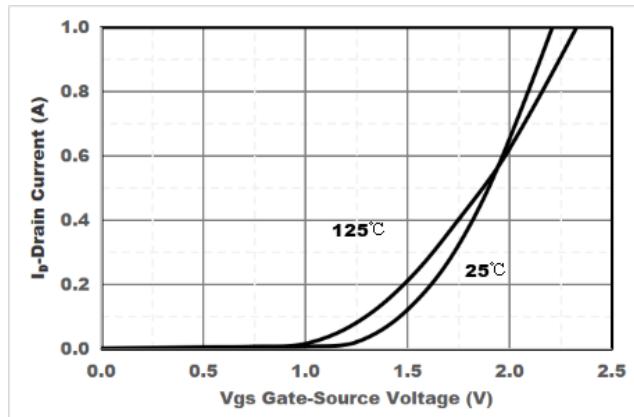


Figure2. Transfer Characteristics

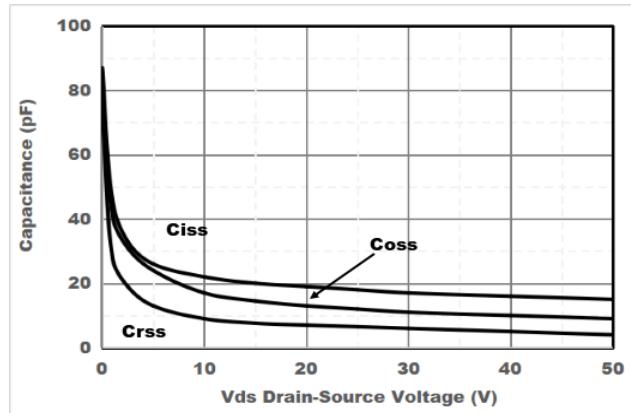


Figure3. Capacitance Characteristics

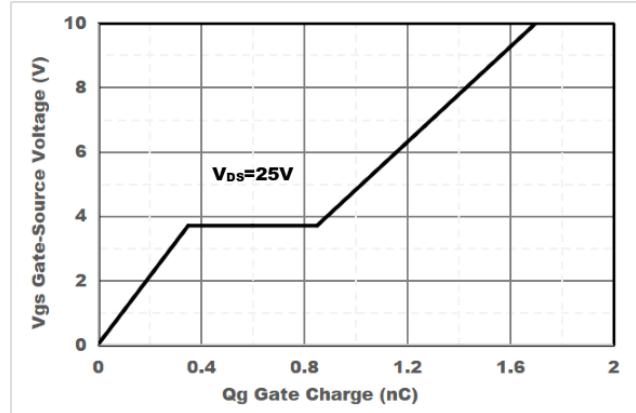


Figure4. Gate Charge

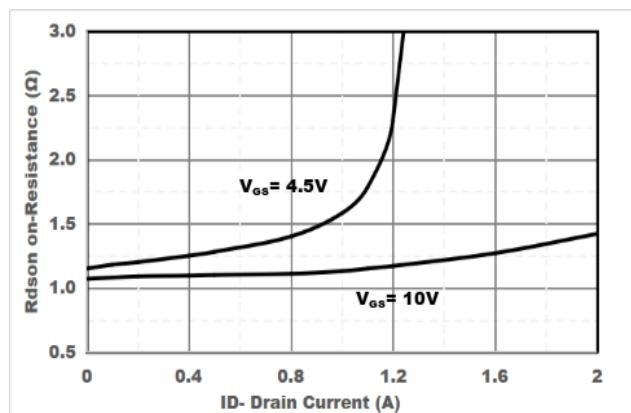


Figure5. Drain-Source on Resistance

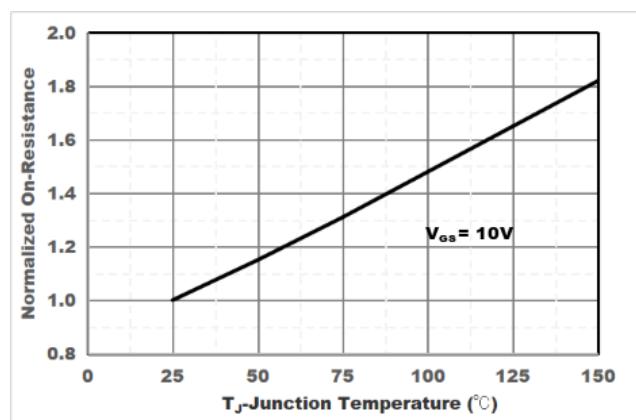


Figure6. Drain-Source on Resistance

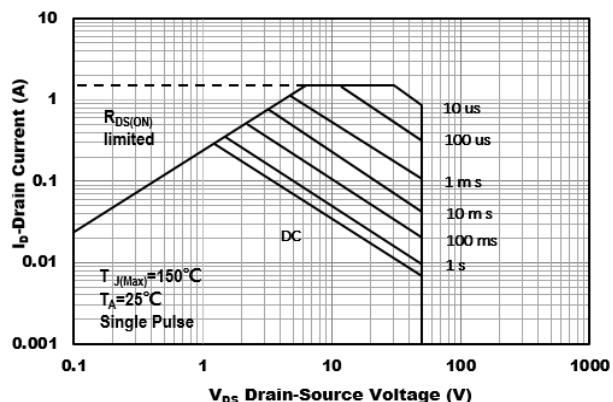


Figure7. Safe Operation Area

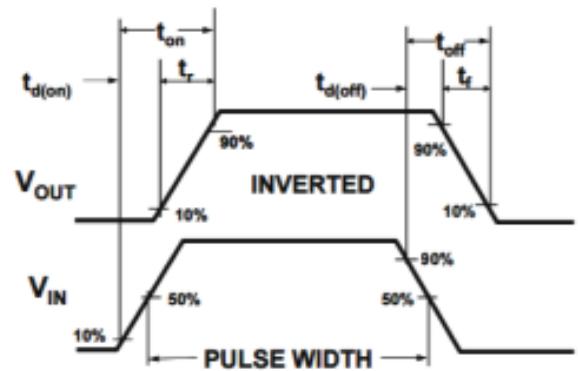
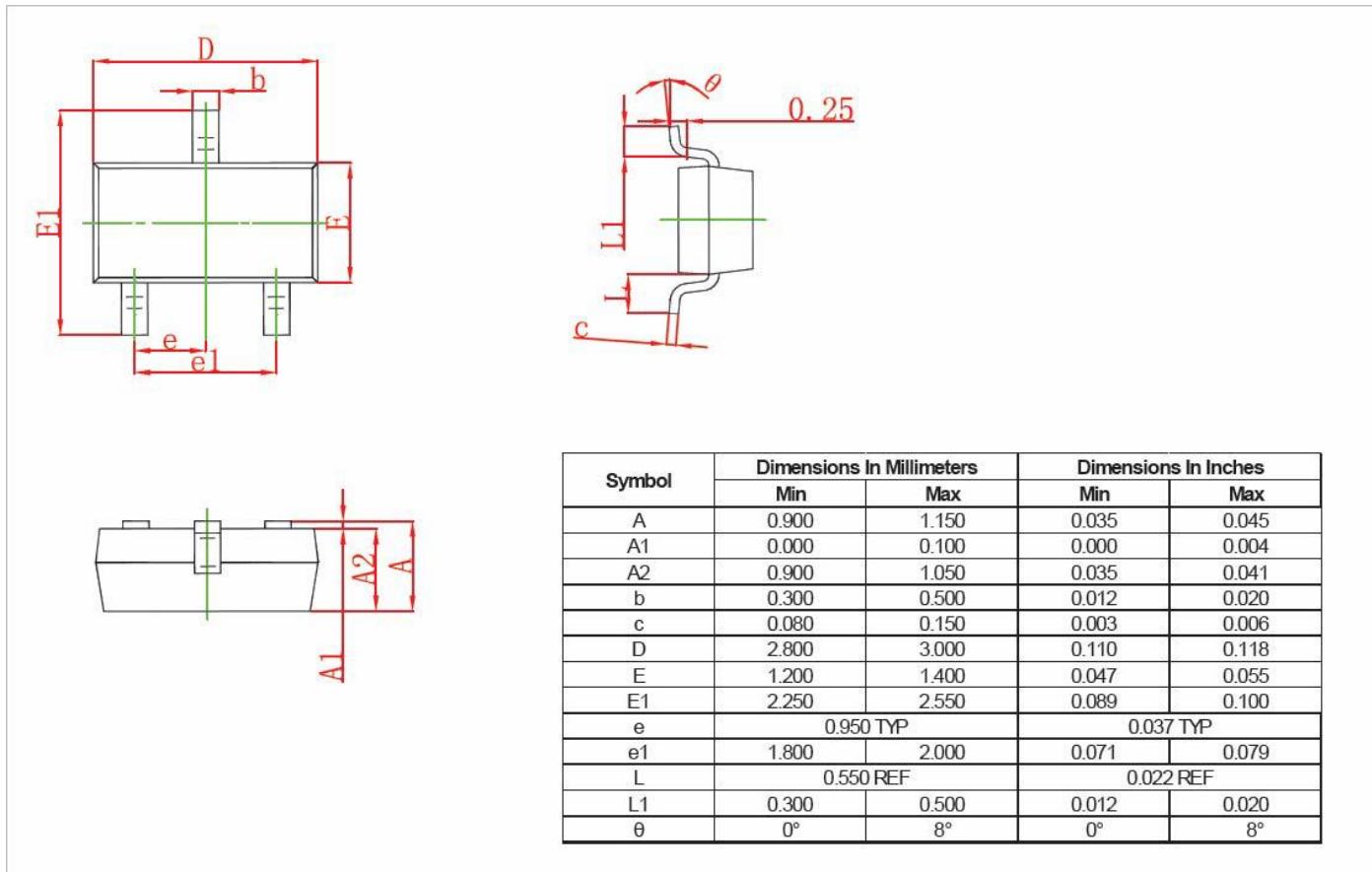
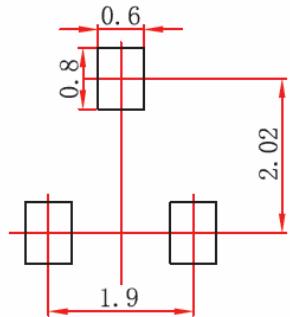


Figure8. Switching wave

■ SOT-23 Package information



■ SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.